



FORM PTO-1449 (MODIFIED)  
LIST OF PATENTS AND  
PUBLICATIONS  
FOR APPLICANTS INFORMATION  
DISCLOSURE STATEMENT

ATTORNEY DOCKET NO.  
SP03-110

SERIAL NO.  
10/648415

APPLICANT: Badding, et al.

FILING DATE:  
August 25, 2003

GROUP: 1745

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
<i>jk</i>	AA	5,733,682	3/31/98	Quadakkers et al	429	210	
<i>jk</i>	AB	6,444,340	9/3/02	Jaffrey	429	30	
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub-Class	Translation Yes	No
<i>jk</i>	AL	DE29807832	7/2/98	Germany	H01M	8/02		X
	AM	WO97/23006	6/26/97	PCT	H01M			
<i>jk</i>	AN	WO00/76015	12/14/00	PCT	H01M	8/10	X	
	AO							
	AP							
	AQ							

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

	AR	
	AS	
	AT	
	AU	
	AV	
	AW	

EXAMINER:

DATE CONSIDERED:

*4/3/06*

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

FORM PTO-1449 (MODIFIED)  LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS INFORMATION DISCLOSURE STATEMENT	ATTORNEY DOCKET NO.	SERIAL NO.
	SP03-110	TBA
	APPLICANT BADDING, et al.	
	FILING DATE HEREWITH	GROUP: TBA

REFERENCE DESIGNATION		U.S. PATENT DOCUMENTS					
Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
<i>AC</i>	AA	5,089,455	2/18/92	Ketcham et al.	501	104	
	AB	5,273,837	12/28/93	Aitken et al.	429	30	
	AC	5,519,191	5/21/96	Ketcham et al.	219	552	
	AD	6,045,935	4/4/00	Ketcham et al.	429	30	
	AE	2002/0102450	8/1/02	Badding et al	429	32	
<i>AC</i>	AF	2003/0096147	5/22/03	Badding et al	429	30	

FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Sub-Class	Translation Yes No
<i>AC</i>	AG	WO 02/088434	11/7/02	PCT	C25D	3/44	
	AH	1 113 518	7/4/01	Europe	H01M	8/12	

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)		
	AI	Minh, N.Q., "Ceramic Fuel Cells", Journal of the American Ceramic Society., Vol. 76, No. 3, pp. 563-588 (1993)
	AJ	Blum et al, "Multi-kW-SOFC Development at Siemens", Solid Oxide Fuel Cells IV, pp. 163-172, 1995.
	AK	Piron et. al., "Ferritic Steel Interconnect for Reduced Temperature SOFC", Solid Oxide Fuel Cells VII, pp. 811-819, 2001.
	AL	Metals Handbook, The American Society for Metals, 1948 Edition, pp. 553-556.
	AM	Miyake et al, "Development of a Planar Solid Oxide Fuel Cell Module at Sanyo", Solid Oxide Fuel Cells (1995), p. 100-109.
	AN	Norton, Robert L., "Designing to Avoid Stress Concentrations", Machine Design, An Integrated Approach, Section 2, p. 235, 1998.
	AO	Timoshenko et al., "Elements of Strength of Materials", p. 29, 1940.
	AP	J. Den Hartog, "Advanced Strength of Materials", p. 48, 1952.
	AQ	Yasuda et al. "Development of Anode-Supported SOFC for Reduced-Temperature Operation", 2000 Fuel Cell Seminar, 2000, Oregon
	AR	Matsuzaki, et al, "Electrochemical properties of a SOFC cathode in contact with a chromium-containing alloy separator", Solid State Ionics, 132, 2000, 271-278
	AS	Jiang, et al., "A comparative investigation of chromium deposition at air electrodes of solid oxide fuel cells", Journal of the European Ceramic Society 22, 2002, 361-373
	AT	Matsuzaki, et al., "Dependence of SOFC Cathode Degradation by Chromium-containing Alloy on Compositions of Electrodes and Electrolytes", Journal of The Electrochemical Society, 148 (2) A126-A131, 2001
	AU	ASM Handbook, Volume 5, Surface Engineering, Anodizing, pg. 482-493
	AV	Metals Handbook, Desk Edition, 16-Heat-Resistant Materials, 16-1
	AW	Peckner, et al., Handbook of Stainless Steels, A1-56
<i>AC</i>	AX	Peckner, et al., Handbook of Stainless Steels, 17-16, Corrosion Resistance

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4/3/06

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